

Automatic Wafer type Laser marker for Sapphire substrate application



Advantage :

- 1) Full automatic : Cassette in and Out. One or Multi-cassettes (4) load port.
- 2) Multi wafer size by one tool : 2", 4" and 6" (or 8") wafer can be done by one tool without hardware exchange.
- 3) Front & Back side marking by one tool.
- 4) Crackless soft mark by UV laser.
- 5) Auto laser power control on marking site.
- 6) High throughput (220wafers/hr possible, depend on mark requirement).
- 7) Semi Standard Fonts : single (5x9 & 9x17) , double (10x19), triple (15x23) density, Barcode 412, ID matrix per SEMI-T2 and T7 standard.
- 8) Compact size by one integrated package.
- 9) Inoization module to remove static charges.
- 10) Cassette bar code reading system (option).
- 11) Vision system (option)- OCR, BC412 and T7 (CRS and BSR) for mark verification.
- 12) SECSII/GEM software (option).
- 13) Robot Plexiglas protection Cover (RPC) (option).
- 14) Infrared protection window (IRW) (option).
- 15) Sorting software module (SSW) (option).
- 16) Slot mapping option (MAP) (option).